Emitter common(dual digital transistor)

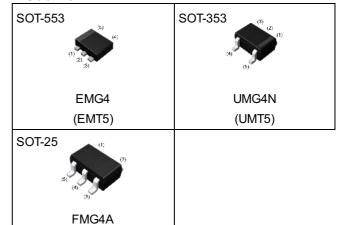
Datasheet

Parameter	DTr1 and DTr2
$V_{\sf CEO}$	50V
I _C	100mA
R ₁	10kΩ

Features

- 1)Two DTC114T chips in a EMT or UMT or SMT package.
- 2) Mounting cost and area can be cut in half.

Outline

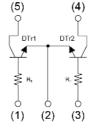


•Inner circuit

EMG4 / UMG4N

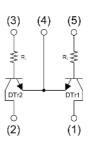
(SMT5)

- (1) DTr1 Base
- (2) DTr1 / DTr2 Emitter
- (3) DTr2 Base
- (4) DTr2 Collector
- (5) DTr1 Collector



FMG4A

- (1) DTr1 Collector
- (2) DTr2 Collector
- (3) DTr2 Base
- (4) DTr1 / DTr2 Emitter
- (5) DTr1 Base



Application

INVERTER, INTERFACE, DRIVER

Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
EMG4	SOT-553 (EMT5)	1616	T2R	180	8	8000	G4
UMG4N	SOT-353 (UMT5)	2021	TR	180	8	3000	G4
FMG4A	SOT-25 (SMT5)	2928	T148	180	8	3000	G4

● Absolute maximum ratings (T_a = 25°C)

<For DTr1 and DTr2 in common>

P	Parameter			Values	Unit
Collector-base voltage			V_{CBO}	50	V
Collector-emitter voltage			V _{CEO}	50	V
Emitter-base voltage			V _{EBO}	5	V
Collector current			I _C	100	mA
	EMG4		P _D *1*2	150	
Power dissipation	UMG4N		P _D *1*2	150	mW/Total
FMG4A		P _D *1*3	300		
Junction temperature			T _j	150	°C
Range of storage temperature			T _{stg}	-55 to +150	°C

● Electrical characteristics (T_a = 25°C)

<For DTr1 and DTr2 in common>

Darameter	Cymabal	Conditions		Values			
Parameter	Symbol	Symbol Conditions		Тур.	Max.	Unit	
Collector-base breakdown voltage	BV _{CBO}	I _C = 50μA	50	-	-	V	
Collector-emitter breakdown voltage	BV _{CEO}	I _C = 1mA	50	-	-	V	
Emitter-base breakdown voltage	BV _{EBO}	I _E = 50μA	5	-	-	V	
Collector cut-off current	I _{CBO}	V _{CB} = 50V	-	-	500	nA	
Emitter cut-off current	I _{EBO}	V _{EB} = 4V	-	-	500	nA	
Collector-emitter saturation voltage	V _{CE(sat)}	I _C = 10mA, I _B = 1mA	-	-	300	mV	
DC current gain	h _{FE}	$V_{CE} = 5V$, $I_C = 1mA$	100	250	600	-	
Input resistance	R ₁	-	7	10	13	kΩ	
Transition frequency	f _T *4	V _{CE} = 10V, I _E = -5mA, f = 100MHz	-	250	-	MHz	

^{*1} Each terminal mounted on a reference land.



^{*2 120}mW per element must not be exceeded.

^{*3 200}mW per element must not be exceeded.

^{*4} Characteristics of built-in transistor.

● Electrical characteristic curves (T_a = 25°C)

<For DTr1 and DTr2 in common>

Fig.1 Grounded Emitter Propagation Characteristics

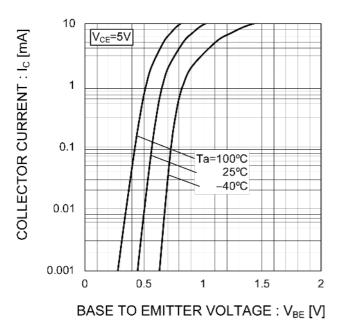


Fig.2 Grounded Emitter Output Characteristics

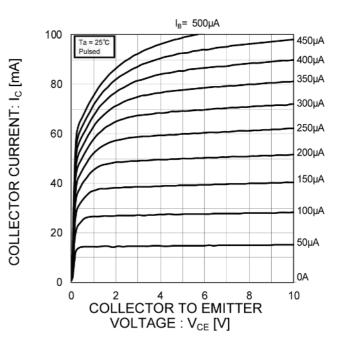


Fig.3 DC Current Gain vs. Collector Current

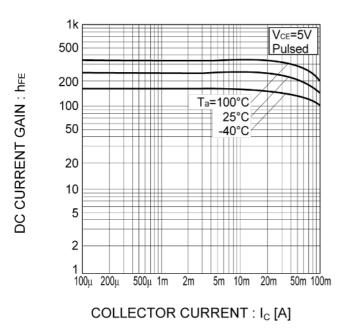
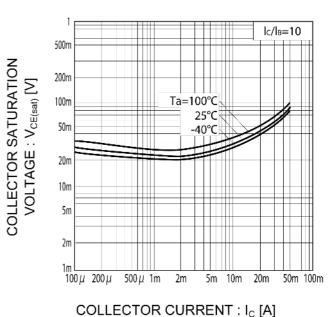
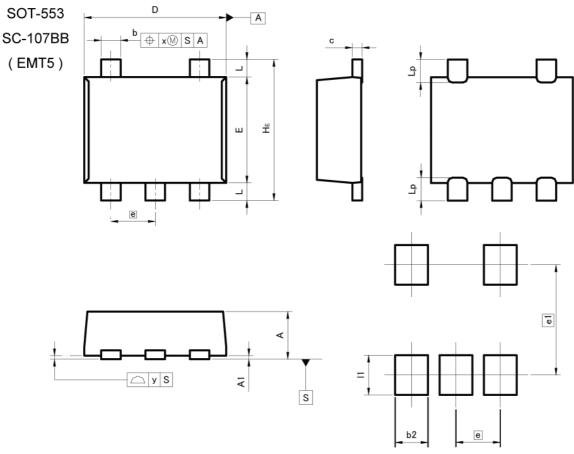


Fig.4 Collector-Emitter Saturation Voltage vs. Collector Current



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

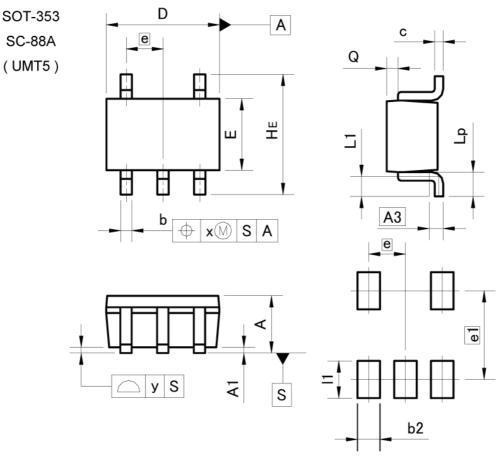
DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
С	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	1.10	1.30	0.043	0.051
е	0.9	50	0.020	
HE	1.50	1.70	0.059	0.067
L	0.10	0.30	0.004	0.012
Lp	-	0.35	_	0.014
х	2	0.10	-	0.004
У	=	0.10	-	0.004

DIM -	MILIMETERS		INCHES	
DIM L	MIN	MAX	MIN	MAX
b2	=:	0.37	_	0.015
e1	1.25		0.0	049
11	=	0.45	=	0.018

Dimension in mm/inches



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

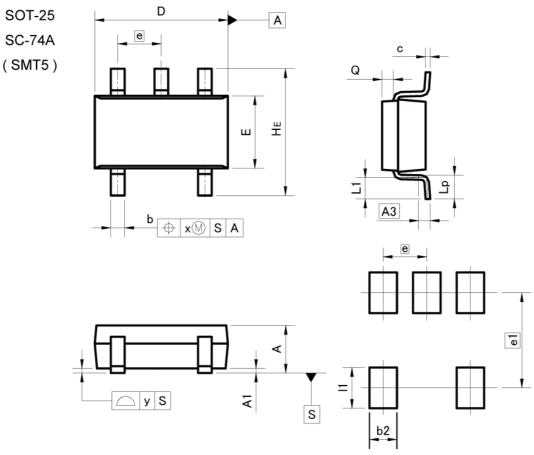
DIM MIN MAX MIN A 0.80 1.00 0.031 A1 0.00 0.10 0.000 A3 0.25 0.0 b 0.15 0.30 0.006 c 0.10 0.20 0.004 D 1.90 2.10 0.075 E 1.15 1.35 0.045 e 0.65 0.0 HE 2.00 2.20 0.079 L1 0.20 0.50 0.008 Lp 0.25 0.55 0.010 Q 0.10 0.30 0.004 x - 0.10 -	ITM	MILIMETERS		HES
A1 0.00 0.10 0.000 A3 0.25 0.0 b 0.15 0.30 0.006 c 0.10 0.20 0.004 D 1.90 2.10 0.075 E 1.15 1.35 0.045 e 0.65 0.0 HE 2.00 2.20 0.079 L1 0.20 0.50 0.008 Lp 0.25 0.55 0.010 Q 0.10 0.30 0.004	M	MAX	MIN	MAX
A3 0.25 0.0 b 0.15 0.30 0.006 c 0.10 0.20 0.004 D 1.90 2.10 0.075 E 1.15 1.35 0.045 e 0.65 0.0 HE 2.00 2.20 0.079 L1 0.20 0.50 0.008 Lp 0.25 0.55 0.010 Q 0.10 0.30 0.004	A 0.	1.00	0.031	0.039
b 0.15 0.30 0.006 c 0.10 0.20 0.004 D 1.90 2.10 0.075 E 1.15 1.35 0.045 e 0.65 0.0 HE 2.00 2.20 0.079 L1 0.20 0.50 0.008 Lp 0.25 0.55 0.010 Q 0.10 0.30 0.004	A1 0.	0.10	0.000	0.004
c 0.10 0.20 0.004 D 1.90 2.10 0.075 E 1.15 1.35 0.045 e 0.65 0.0 HE 2.00 2.20 0.079 L1 0.20 0.50 0.008 Lp 0.25 0.55 0.010 Q 0.10 0.30 0.004	A3	0.25	0.0	10
D 1.90 2.10 0.075 E 1.15 1.35 0.045 e 0.65 0.0 HE 2.00 2.20 0.079 L1 0.20 0.50 0.008 Lp 0.25 0.55 0.010 Q 0.10 0.30 0.004	b 0.	0.30	0.006	0.012
E 1.15 1.35 0.045 e 0.65 0.0 HE 2.00 2.20 0.079 L1 0.20 0.50 0.008 Lp 0.25 0.55 0.010 Q 0.10 0.30 0.004	c 0.	0.20	0.004	0.008
e 0.65 0.0 HE 2.00 2.20 0.079 L1 0.20 0.50 0.008 Lp 0.25 0.55 0.010 Q 0.10 0.30 0.004	D 1.	2.10	0.075	0.083
HE 2.00 2.20 0.079 L1 0.20 0.50 0.008 Lp 0.25 0.55 0.010 Q 0.10 0.30 0.004	E 1.	1.35	0.045	0.053
L1 0.20 0.50 0.008 Lp 0.25 0.55 0.010 Q 0.10 0.30 0.004	е	0.65		26
Lp 0.25 0.55 0.010 Q 0.10 0.30 0.004	HE 2.	2.20	0.079	0.087
Q 0.10 0.30 0.004	_1 0.	0.50	0.008	0.020
	_p 0.	0.55	0.010	0.022
x - 0.10 -	Q 0.	0.30	0.004	0.012
	х	0.10	\$ 	0.004
y – 0.10 –	у	0.10		0.004
			siglis.	

DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
b2	 A	0.40	× 	0.016
e1	1.55		0.0	061
H	u s	0.65	8 10	0.026

Dimension in mm/inches



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.:	25	0.0	10
b	0.25	0.40	0.010	0.016
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.9	95	0.0	37
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
х	55 6	0.20	₩.	0.008
У	1 11 3)	0.10	THE S	0.004

DIM	MILIM	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
b2	THE .	0.60	TH.	0.024
e1	2.10		0.0	083
11	=8	0.90	 20	0.035

Dimension in mm/inches



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Ī	JÁPAN	USA	EU	CHINA
Ī	CLASSⅢ	CLACCIII	CLASS II b	CL ACCIII
	CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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